

South East Asia Technical Training Conference on Electronics Assembly Technologies 2018

Tuesday, August 14

Conference and Course

7:30am	Registration	Speaker
8:50am	Opening Comments	
	Session 1: Inspection Technology	Session Chair: Kong Hui Lee., Ph.D., Cisco Systems
9:00am	New LED Technology Challenges for X-Ray	Keith Bryant, Yxlon International
9:30am	In Situ Imaging of Microstructure Formation in Lead and Lead-Free Electronic Interconnections	Mohd Arif Anuar Mohd Salleh, Universiti Malaysia Perlis
10:00am	Advances in 2D and 3D (CT) X-Ray Inspection for Electronics in Harsh Environments	Keith Bryant, Yxlon International
10:30am	Networking Break	
	Session 2: Big Data Analytic and Manufacturing Excellence	Session Chair: Mei-Ming Khaw, Keysight Technologies
11:00am	A Smarter Approach to Big Data Analytics on Procurement	Ai Kiar Ang, IBM
11:30am	A Holistic Approach for Technology and Quality Audits in the New Era of Computer Servers Design and Manufacturing	Ron Yin, IBM
12:00pm	Using Six Sigma DMAIC Process Approach to Optimize Manufacturing Test Time	Kong Hui Lee., Ph.D., Cisco Systems
12:30pm	Lunch	
	Professional Development Course	
1:30pm	PDC1 Flip Chip, WLCSP, and FOWLP Assembly and Reliability John Lau, Ph.D., ASM	
5:00pm	Day 1 Conclusion	

Wednesday, August 15

Conference, Learning Lab, Penang Expo and Soldering Competition

8:00am	Registration	Speaker
	Session 3: Cleaning Challenges and Industry Technology Advancement	Session Chair: Mei-Ming Khaw, Keysight Technologies
9:00am	Industry 4.0 for Inspection for Electronics Industry	Ragnar Vaga, Yxlon International GmbH
9:30am	Visual Evidence of the Cleaning Process using a Custom Design Test Vehicle	TC Loy, KYZEN Corporation
10:00am	Networking Break	
	Session 4: Advanced Packaging and Design	Session Chair: Koh Yee May, Keysight Technologies
10:30am	KEYNOTE: Recent Advances in Flip Chip, WLCSP, and FOWLP	John Lau, Ph.D., ASM
11:15am	Automotive Power Module Advanced Packaging Assembly Solution	John Almiranez, Universal Instruments
11:45am	Innovation on Shield Lid Design	Jui Ang Tan, Intel Corporation
12:15pm	3D Interconnects – The Enabler of Next Generation Multi-Gbps Single-Ended Bus	Khang Choong Yong, Intel Corporation
12:45pm	Lunch	
	Session 5: Solder Paste and Soldering Technology	Session Chair: John Almiranez, Universal Instruments
2:00pm	Solder Paste Technology for Next Generation Assembly	Ansuman Das, Alpha Assembly Solutions
2:30pm	Low Voiding Lead-Free Solder Paste for High Reliability Applications	Steven Teh, Inventec Performance Chemicals SEA Sdn. Bhd.
	Learning Lab	
3:00pm	Understanding Parameters Affecting Barrel Fill in Wave Soldering Process AF Ng, Techment Consultancy Sdn. Bhd.	
5:00pm	Day 2 Conclusion	